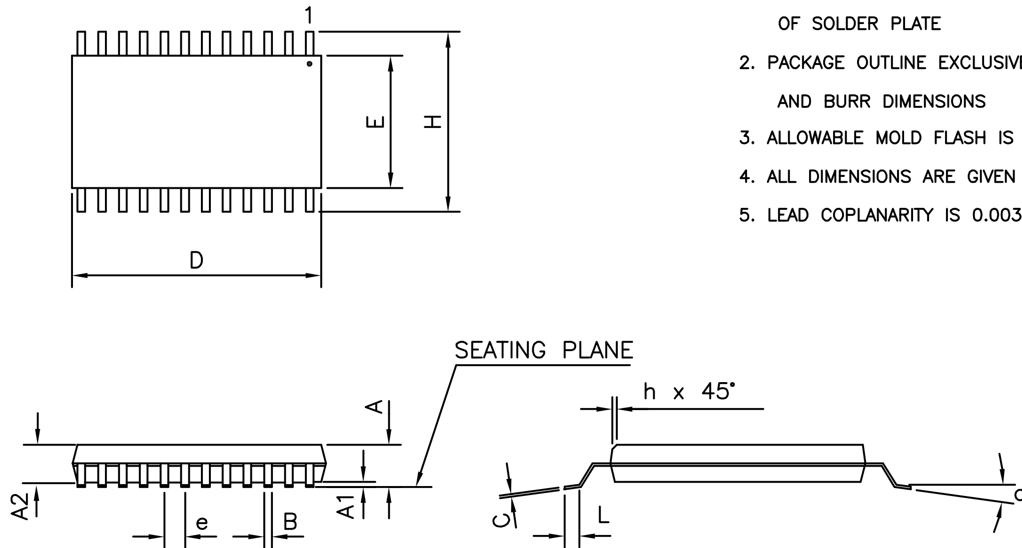
173 MIL TSSOP
Thin Shrink Small Outline Package (TSSOP)

PACKAGE INFORMATION



NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. ALL DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.

JEDEC#	MO-153AA		MO-153AC		MO-153AD	
TYPE	08 LEAD		20 LEAD		24 LEAD	
SYMBOL	Min	Max	Min	Max	Min	Max
A	0.034	0.047	0.034	0.047	0.034	0.047
A1	0.002	0.006	0.002	0.006	0.002	0.006
B	0.007	0.012	0.007	0.012	0.007	0.012
C	0.004	0.008	0.004	0.008	0.004	0.008
D	0.114	0.122	0.252	0.260	0.303	0.311
E	0.169	0.177	0.169	0.177	0.169	0.177
e	0.0256 BSC		0.0256 BSC		0.0256 BSC	
H	0.252 BSC		0.252 BSC		0.252 BSC	
L	0.020	0.030	0.018	0.030	0.018	0.030
a°	0°	8°	0°	8°	0°	8°

PREPARED BY	NK	REF. NO.	REV. NO.	SPEL SEMICONDUCTOR LIMITED
CHECKED BY	SS	DIM-TSOP-02	2	INDIA
APPROVED BY	NJC		DATE 24.10.05	